

SEMICONDUCTOR INTERNATIONAL

1984 Article Index

This complete index of articles and authors covers the various subjects published in *Semiconductor International* in 1984. The listings are by article under the following categories: Processing, Assembly and Testing; Company Profiles; Business and Market Indicators; and Conference, Exhibitions and Previews. The Author Index at the end of this section indicates the month and page in which an author's work appeared. Reprints are available on a custom basis at reasonable prices in quantities of 500 or more. Contact Art Lehmann, Cahners Publishing Co., Reprint Services, Cahners Plaza 1350 E. Touhy Ave., P.O. Box 5080, Des Plaines, Ill. 60018 (312) 635-8800.

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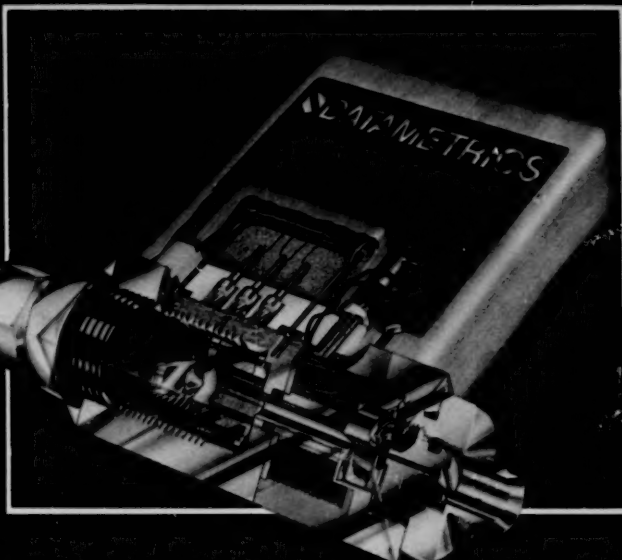
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